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Developing secure IoT systems as fast as possible

Cadence and Arm Seminar 2018

Petach Tikvah, Israel

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- Phil Burr, Director, Embedded Portfolio, Arm
Bernd Reinkemeier, Senior Technical Executive, Cadence
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What are today's embedded and IoT challenges?



- Extreme low-power
- Integration complexity
 - Many elements
 - Logic, memory, flash, mixed signal, RF, power, sensors...
- Long life, in remote location
- Security
- Very low cost

Challenges vary across types of devices

Constrained



- Ultra-low-cost, simple sensors
- Often battery powered
- Connecting to gateway or cloud

Mainstream



- Balancing performance and cost
- Moderate data or audio capabilities
- High power efficiency

Rich IoT nodes & gateways



- High levels of data processing at edge
- Autonomous decision making or machine learning
- Providing gateway to cloud

Security is a common challenge across all devices

Constrained



Mainstream



Rich IoT nodes & gateways



- Ultra
- Of
- Conn

- ssing at edge
- ing or ML
- ud

Security – a key requirement for all

Arm's Platform Security Architecture (PSA)

Consistently design in the right level of security into low-cost IoT devices

Analyze



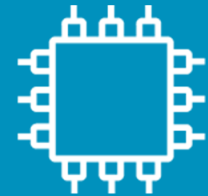
Threat models
& security analyses

Architect

Hardware & firmware
architecture
specifications



Implement



Firmware source code



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What are we protecting against? Threat modelling

Communications

- Man-in-the-middle
- Weak RNG
- Code vulnerabilities

Physical

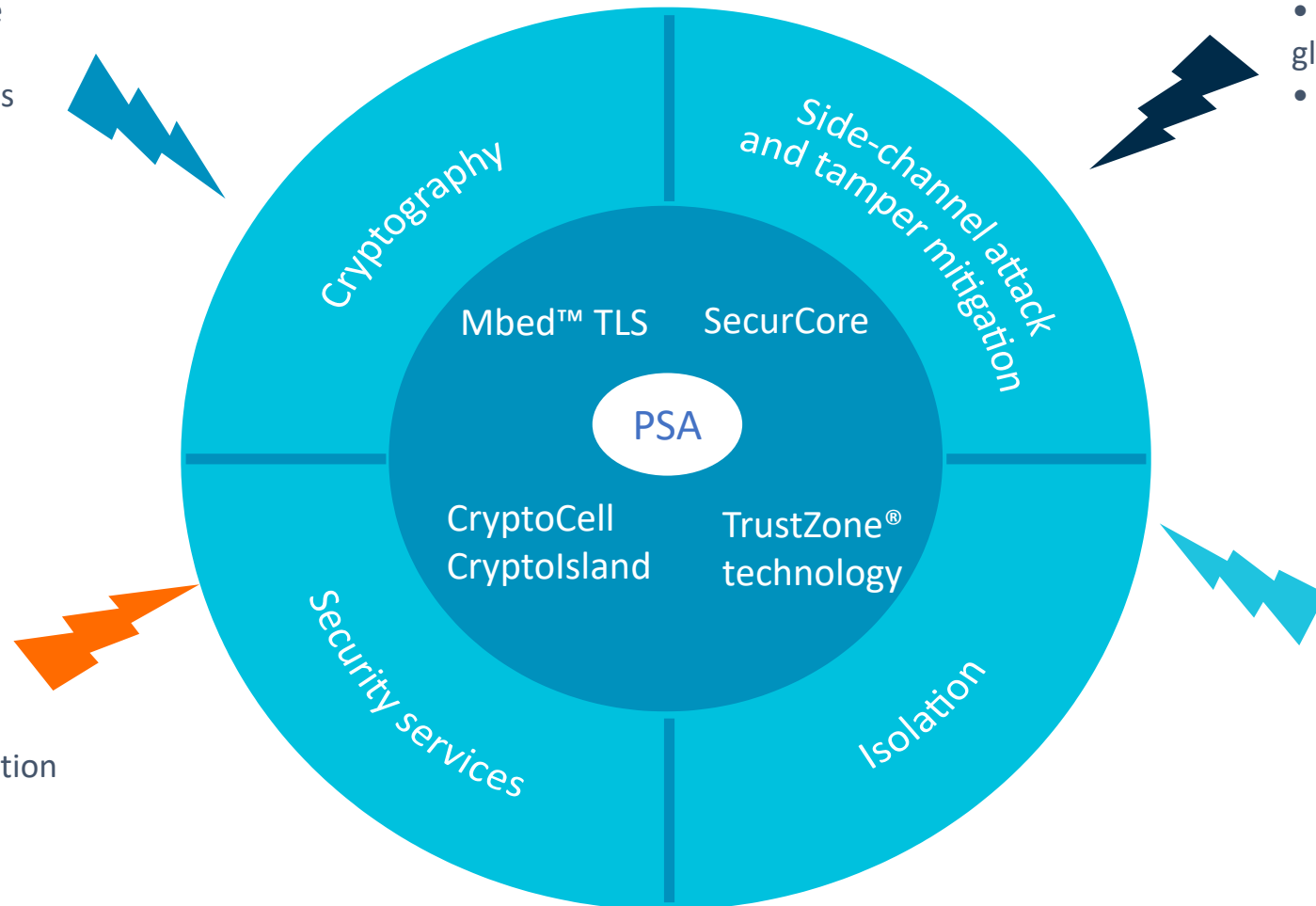
- Non-invasive (e.g. clock, power glitch or SCA)
- Invasive: package removal (e.g. microprobe station FIB)

Lifecycle

- Code downgrade
- Change of ownership or environment
- Unauthorized overproduction

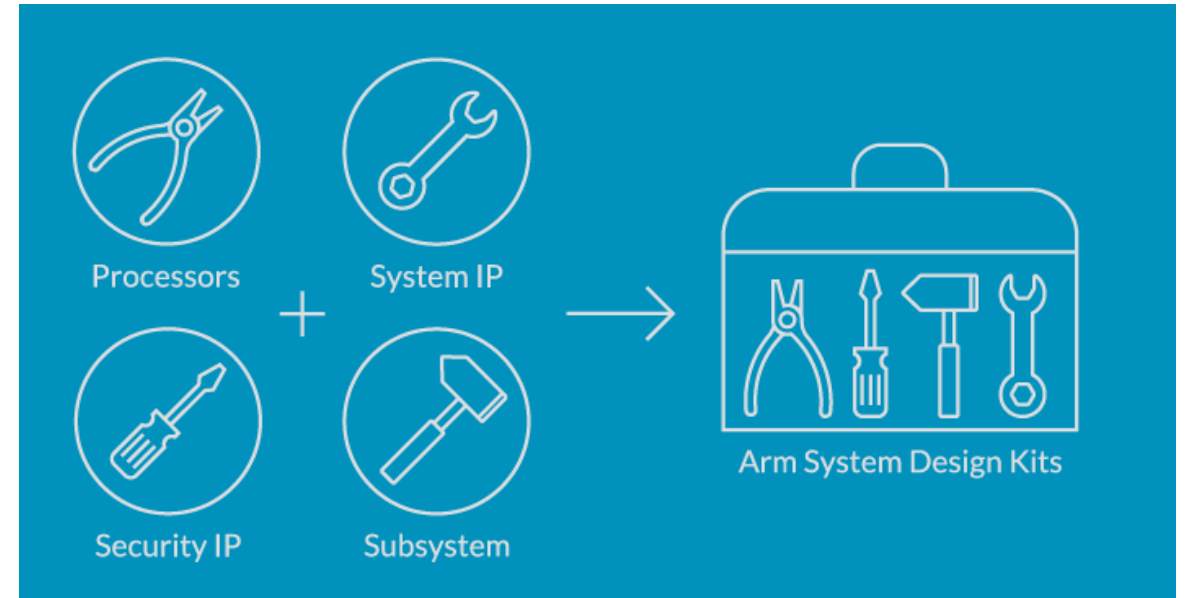
Software

- ROP (e.g., buffer overflows)
- Interrupts
- Malware



Arm SoC solutions: A complete toolbox for SoC designers

- Standardized interfaces and architecture, common software development
- Pre-verified and pre-integrated foundation
- Extendable for differentiation and diversity of applications
- Bring your secure SoC to market fast, with lower risk



There are subsystems for each class of device

Constrained



SSE-050

Mainstream



SSE-200

Rich IoT nodes & gateways



SDK-700

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SSE-050 subsystem (part of SDK-101 / SDK-200)

A fast way to start in IoT

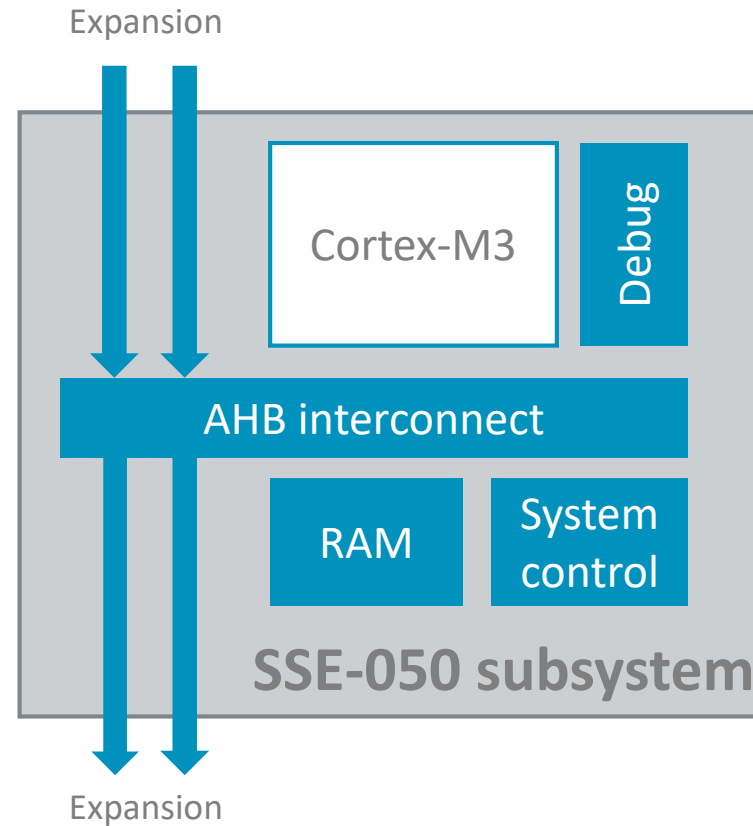
Compact

- Based on Cortex-M3

Good starting point

Software support

- Mbed OS
- Other RTOS



SSE-200 subsystem (part of SDK-200)

A reference system to build secure systems with TrustZone technology

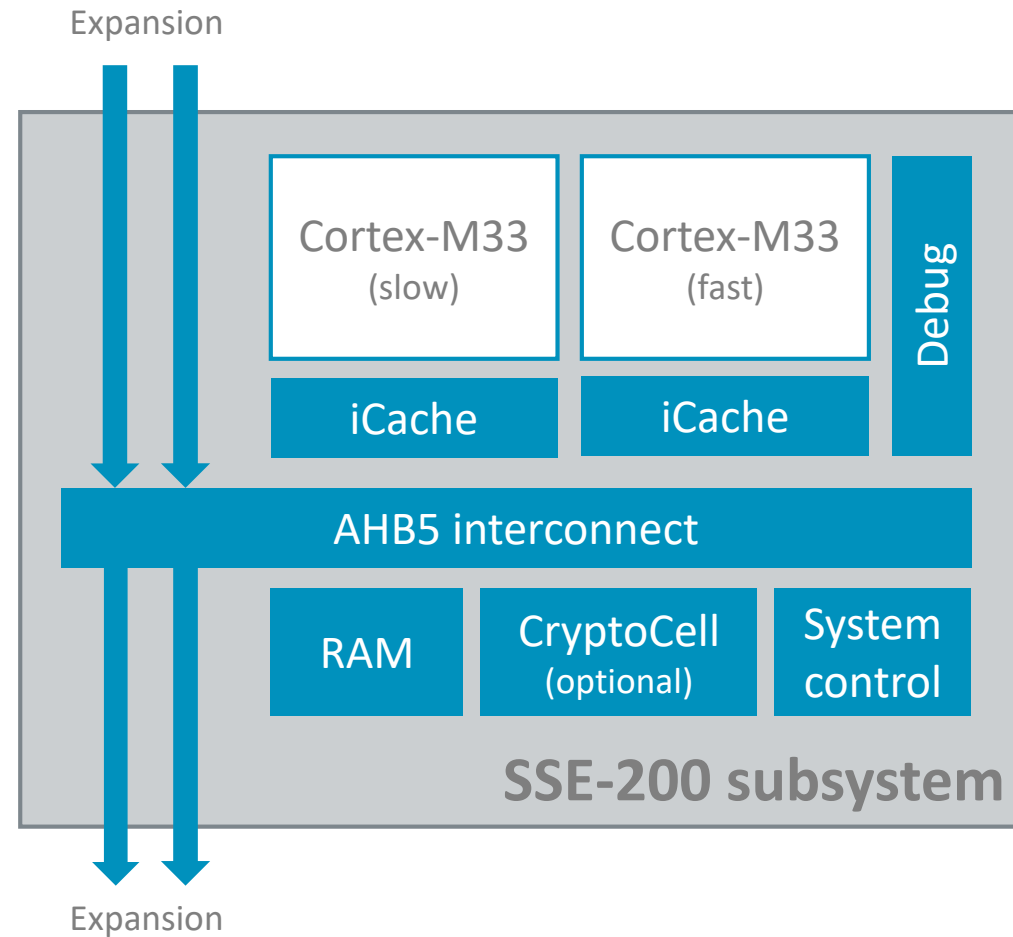
Using Cortex-M33

- Armv8-M architecture

Built for IoT

- Fine-grain power control
- Asymmetric processing
- Always-on domain

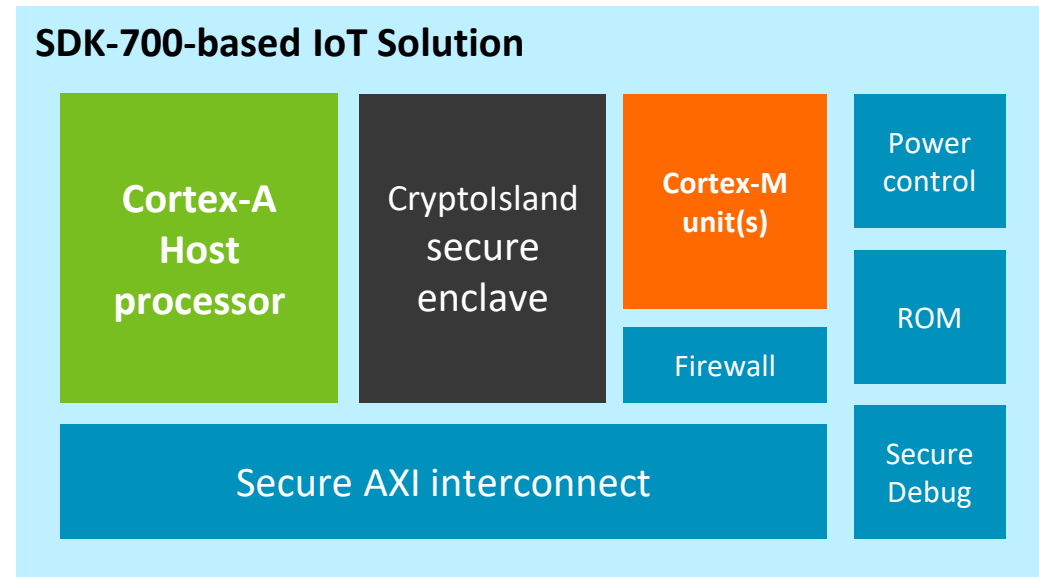
PSA ready



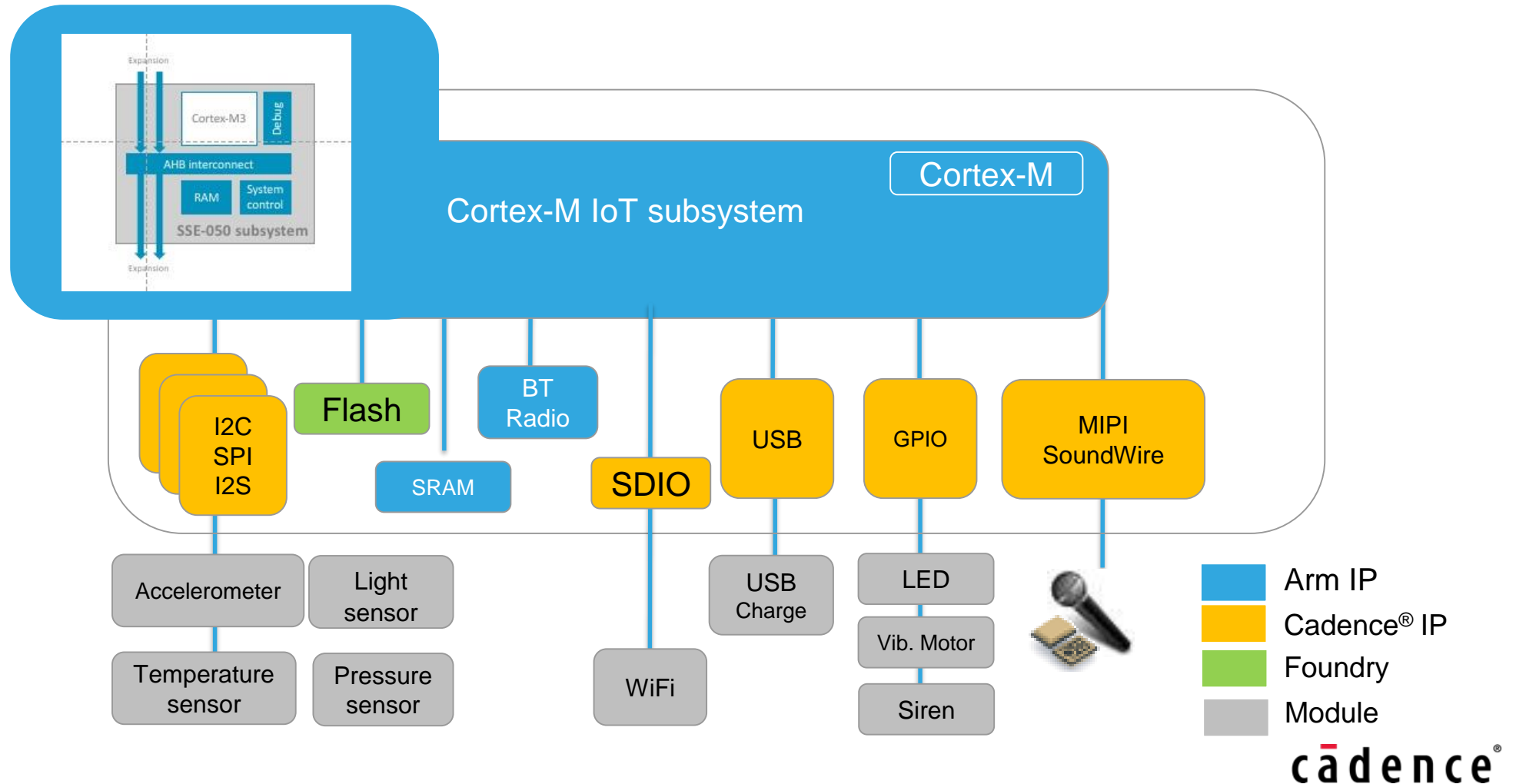
Arm SDK-700 System Design Kit

A new flexible SoC solution for rich IoT nodes and gateways

- Flexible compute
 - Arm® Cortex®-A – performance & rich OS
 - Arm Cortex-M – real-time & highest efficiency
- Secure SoC foundation
 - Supports Microsoft Azure Sphere
- Built on PSA principles
 - Secure system architecture
 - Common software architecture

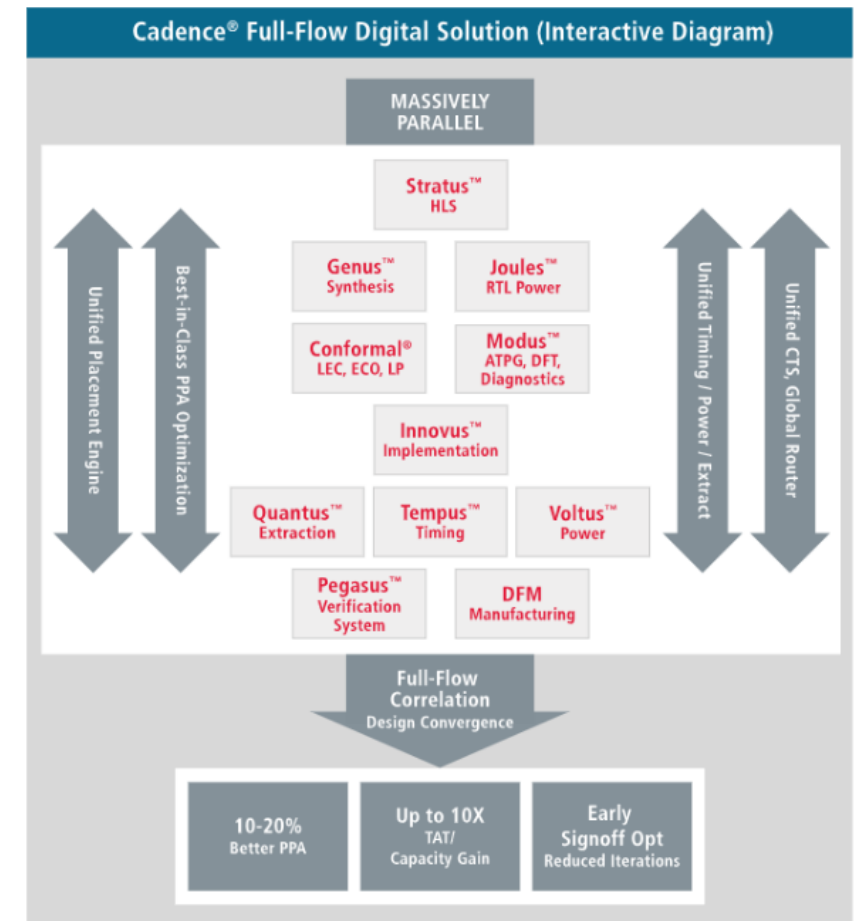


Extending Arm's subsystem with Cadence IoT IP



Cadence Rapid Adoption Kit (RAK) for Arm Cortex-M23 and Cortex-M33

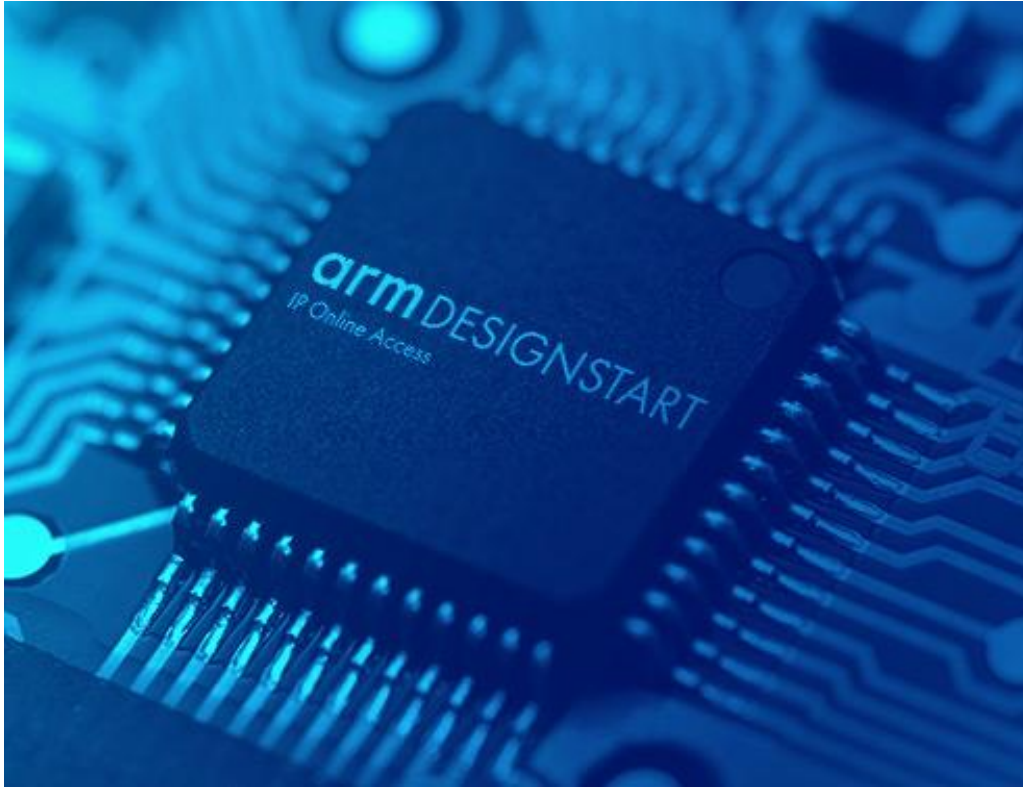
- Quick path to implementation via a full-flow digital and signoff reference methodology that provides optimal power, performance and area (PPA)
- Achieve fast runtimes and efficient design closure through the integrated Cadence RTL2GDS
- Implement IoT devices using the complete Cadence low-power flow: design, verification, implementation



For accessing Cadence RAKs, contact your local Cadence office and support AE

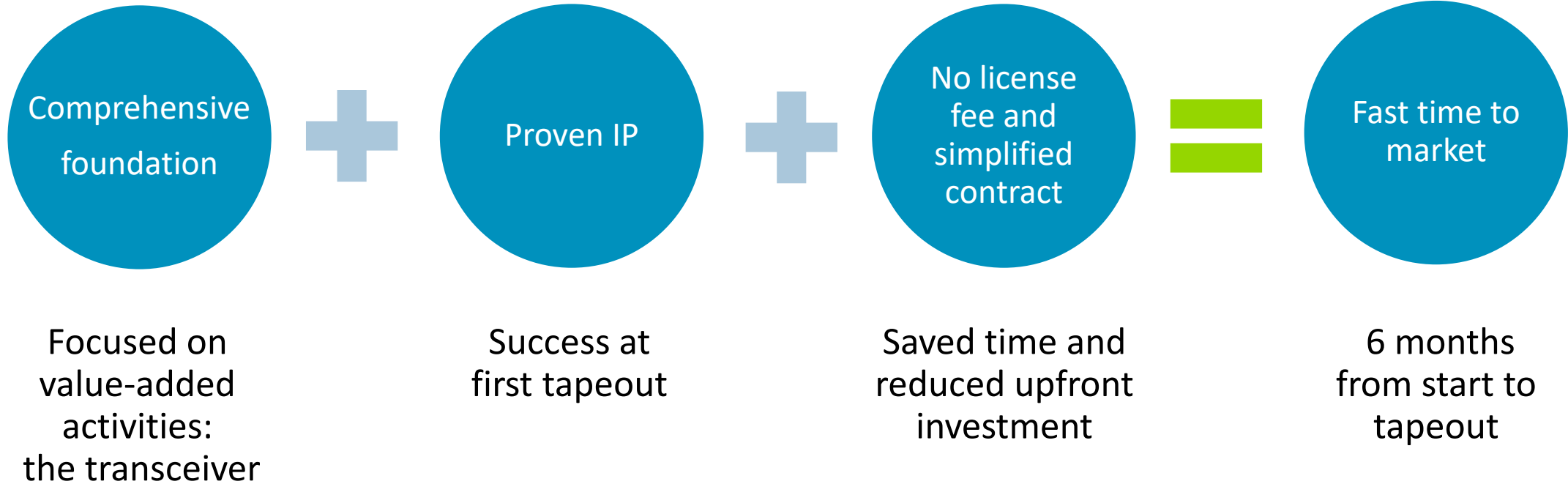
Building a chip yourself? Use Arm DesignStart™ portal

Fast access to industry-leading processor IP and physical IP – for no upfront fee



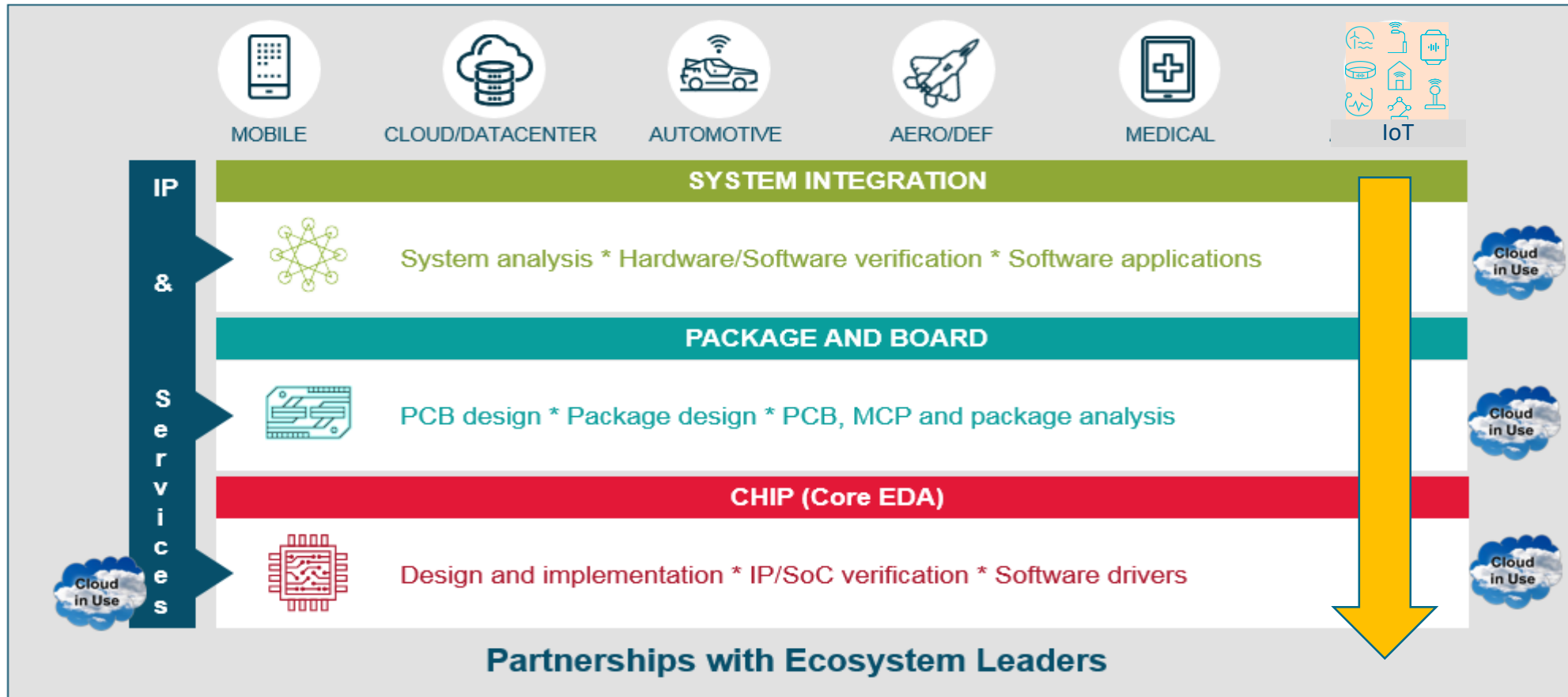
- Simple, quick web-based access to Arm IP
- Leading Cortex-M processors and subsystems
- System design kits with pre-verified subsystems for faster development
- Access to Cadence tools, support, and methodologies in Hosted Design Solution chamber
- 1000s of physical IP libraries
- Used in 1000s of SoC designs

Case study: Speeding time to market with proven Arm IP



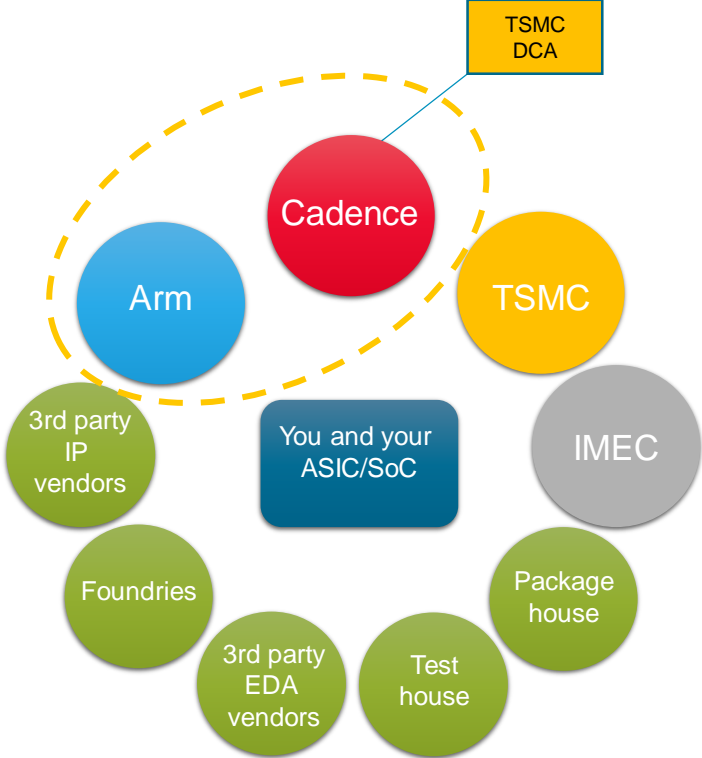
Cadence System Design Enablement

Holistic and scalable design solution for enabling IoT differentiated products



Cadence SDE: Vertical markets enablement

EMEA SDE Competency	Automotive	AI ML/DL	HPC	5G	Mil/Aero	Imaging	IoT
System architecture	Green	Green	Green	Green	Grey	Green	Green
HW/SW partitioning	Green	Green	Green	Green	Green	Green	Green
HW emulation and acceleration	Green	Green	Green	Green	Green	Green	Green
IP and IP integration	Green	Green	Green	Green	Green	Green	Green
Design and verification	Green	Green	Green	Green	Green	Green	Green
Functional safety	Green	Grey	Grey	Grey	Green	Grey	Grey
DFT	Green	Green	Green	Green	Green	Green	Green
Phys implementation and signoff	Green	Green	Green	Green	Green	Green	Green
Package and board	Green	Green	Green	Green	Green	Green	Green



Design Infrastructure

High-Speed Processor SS

Library Characterization

SCM (Interface)



Reduce complexity, risk, and cost

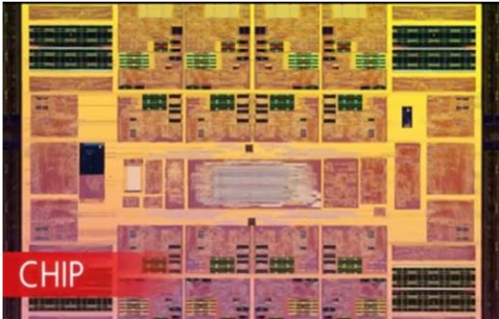
Concept Phase



System architecture

SoC Development

Prototyping

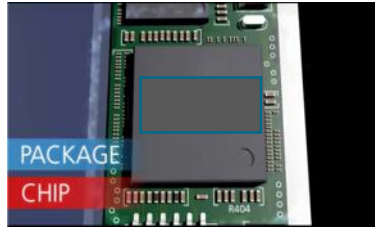
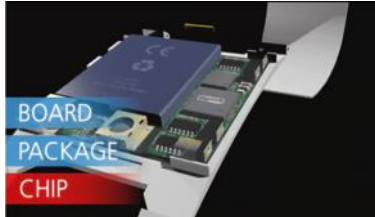
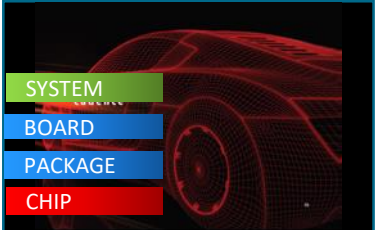


Verification

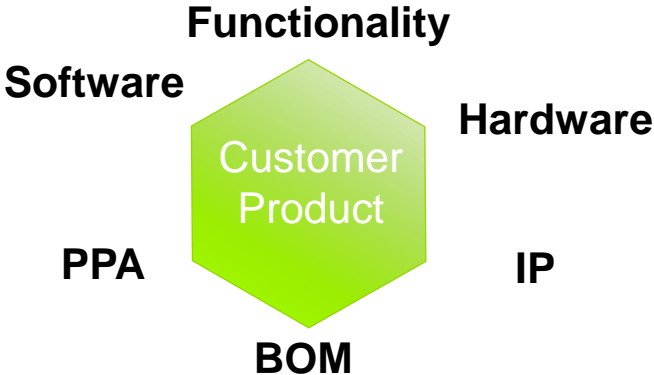
Design

Implementation

System Integration



BOM



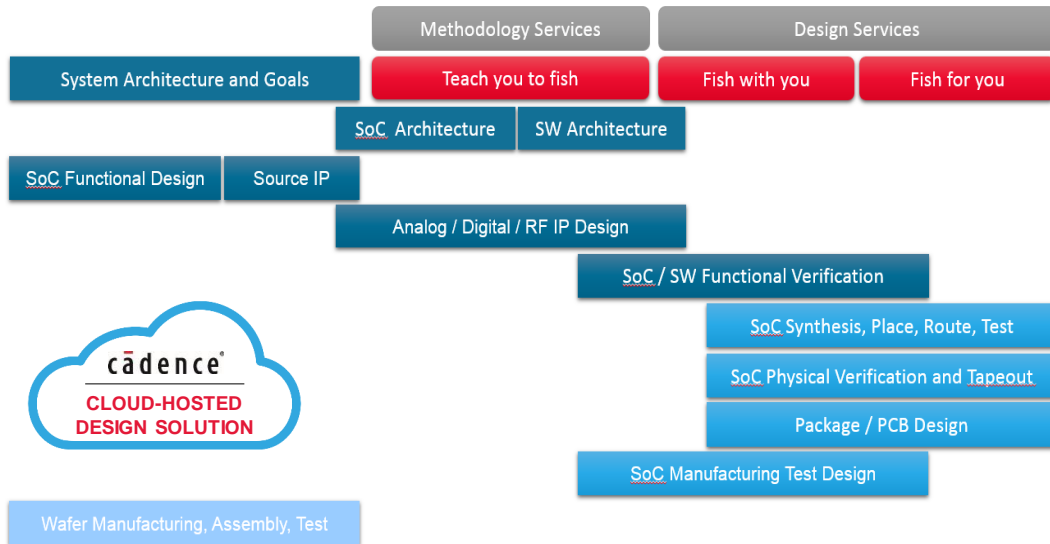
CAD foundation
(EDA SW)



Cadence and Arm Design Enablement

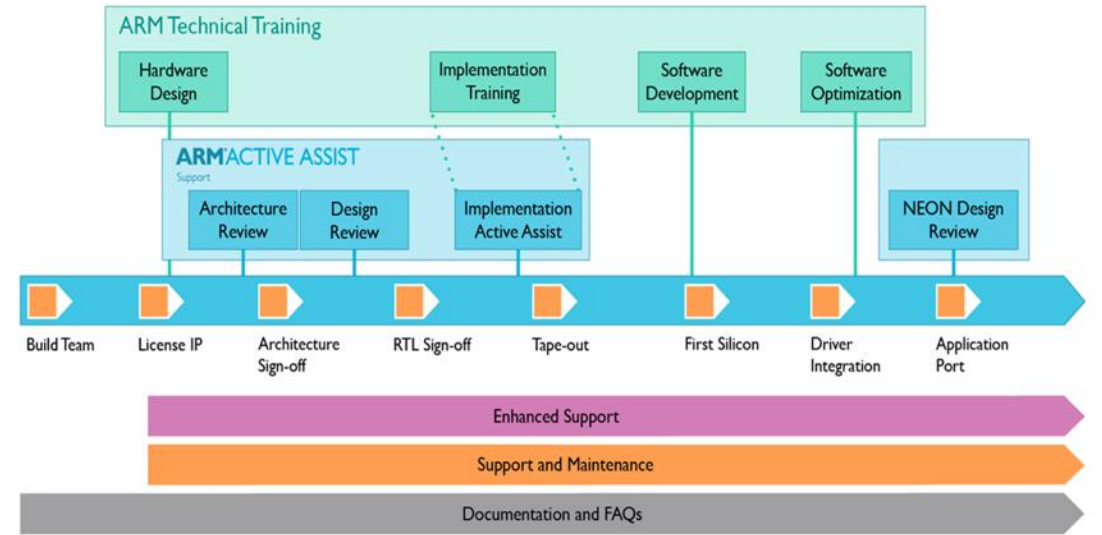
Need SoC design help?

Need SoC Design Help?.. Cadence Can Help! Methodology and Design Services



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Need SoC Design Help?.. ARM Can Help! The help you need, when you need it



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Some key risks in ASIC/SoC design – Cadence can help you

Risk area

- Design complexity rising
- RTL-GDSII implementation
- IC-package-board co-design
- Hardware-software coherence
- Analog/mixed to digital interfacing
- IP integration

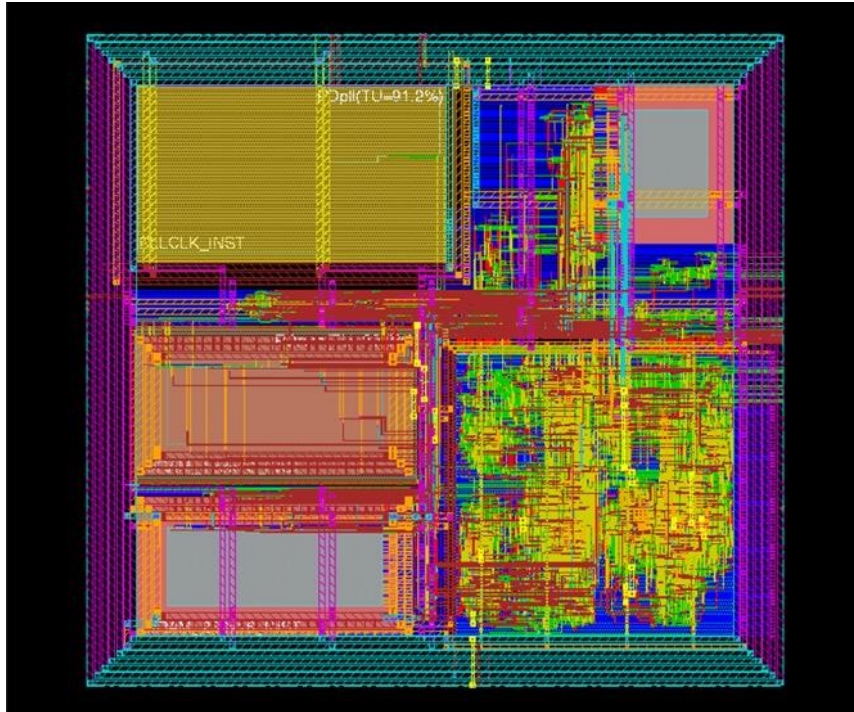
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Cadence offers

- One of the strongest SoC verification methodology & services teams in the industry
- RTL-GDSII implementation methodology
 - 200+ tapeouts in last 5 years, spanning 180nm to 3nm! Many Arm-based designs.
- SI/PI/thermal analysis and optimization
- SoCs stress testing
- Analog/mixed-signal/RF design & verification
- A broad IP portfolio with integration support

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There is mixed signal in IoT



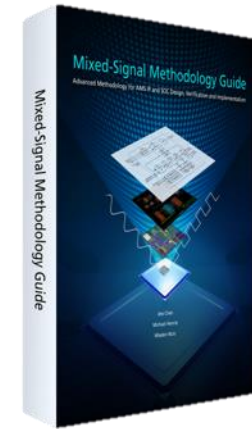
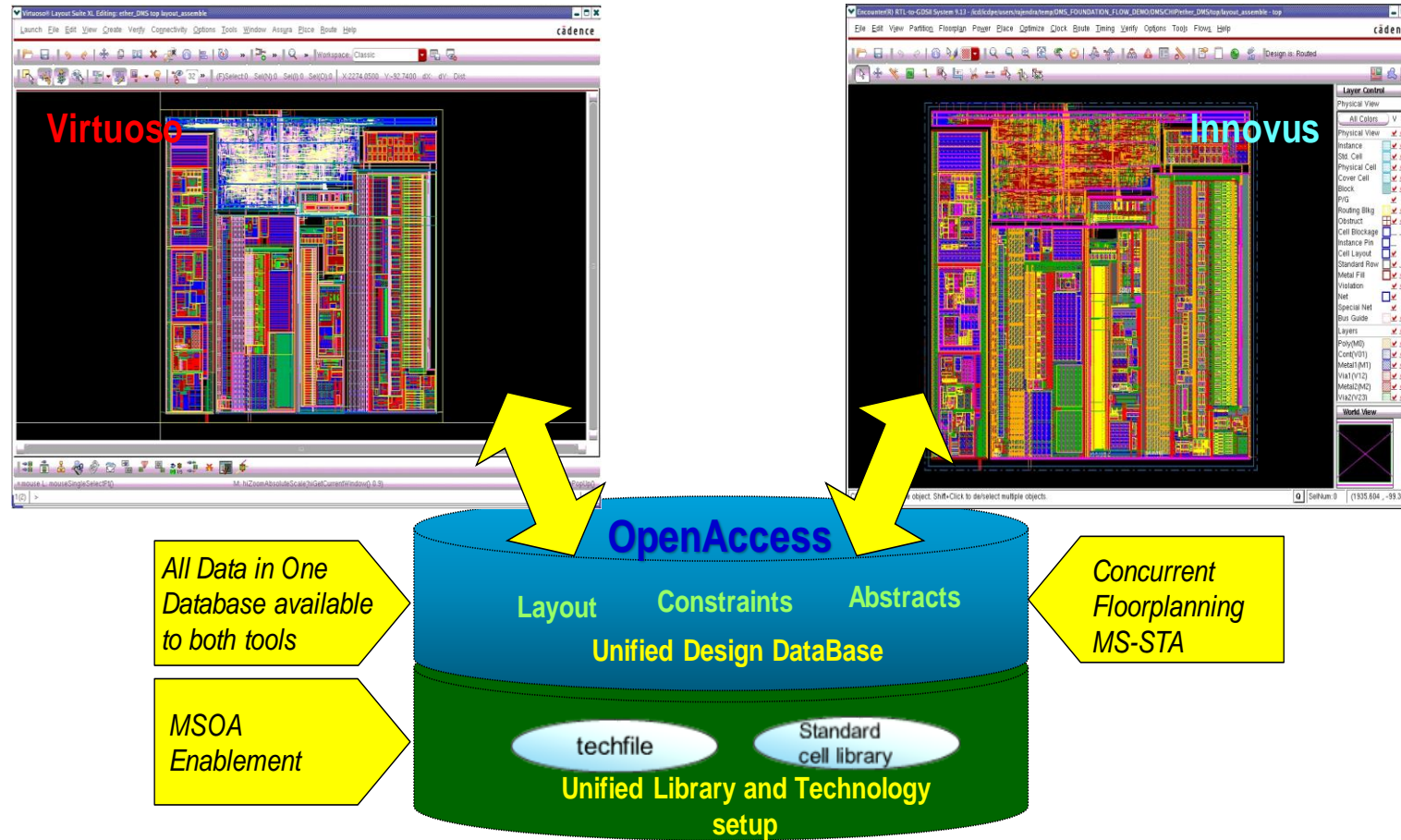
Source: 2013 © Semico Research Corp. All Rights Reserved
System(s)-on-a-Chip: *Changes in SoC Design Methodology*

Reasons for re-spins in analog mixed-signal SoCs

1. Logical and functional errors
2. Clocking issues
3. Analog–digital interfaces
4. Crosstalk
5. Power management
6. Analog circuits
7. Yield/reliability
8. Timing
9. Firmware
10. IR drops

Cadence solution for mixed signal

Cadence Mixed-Signal Flow has produced many thousands of successful tapeouts



Cadence Mixed-Signal Methodology Guide
ISBN: 978-1300035206

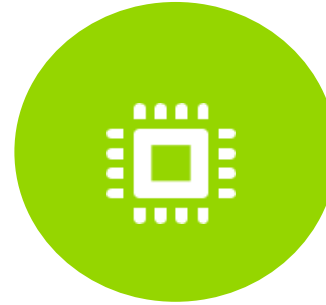
IoT is quicker, easier and more flexible with Arm Cadence design solutions



Low power,
scalable compute



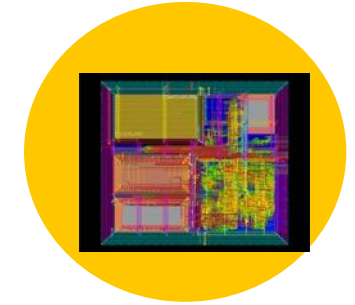
Security, identity
& platform security
architecture



Configurable
SoC
frameworks



OS & tools



Design assistance

Arm: System-level solutions to simplify IoT development and deployment:
Secure, scalable, configurable, and power efficient

Cadence: Low-power solution, IoT System Design Enablement (IP, software,
hardware, methodology, design services), cloud-hosted design solution

Thank You

Danke

Merci

谢谢

ありがとう

Gracias

Kiitos

감사합니다

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